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Docket No.: YUSO-131

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PATENT APPLICATION TRANSMITTAL

Box Patent Application
Commissioner for Patents & Trademarks
Washington, D.C. 20231

Jc979 U.S. PTO
10/05/2989
11/09/01

Transmitted herewith for filing under 35 U.S.C. 111 and 37 C.F.R. 1.53 is the patent application of:

INVENTOR(S): Han-Kun Hsieh; Shing-Ru Wang; I-Chung Tung

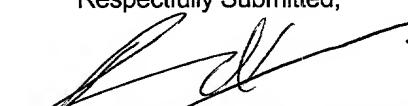
FOR: FORMATION OF ELECTROPLATE SOLDER ON AN ORGANIC CIRCUIT BOARD FOR FLIP CLIP JOINTS AND BOARD TO BOARD SOLDER JOINTS

Enclosed are:

- (X) Specification (17 pgs)
(X) 9 sheets of formal drawings
(X) Declaration and Power of Attorney
(X) A copy of the priority document for Taiwan Patent Application No. 90118363 filed 7/27/01, from which priority is claimed
(X) An assignment and Assignment Recordation and a check for \$40
(X) A check in the amount of \$878 to cover the filing fee is enclosed

	Number Filed	Number Allowed	Number Extra	Rate	Large Entity Fee
Total Claims	23	20	= 3 x	\$18 =	\$54
Indep. Claims	4	3	= 1 x	\$84 =	\$84
Basic Fee					\$740
TOTAL =					\$878

Respectfully Submitted,



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Date: 11-9-01

CERTIFICATE OF MAILING

I hereby certify that the above-identified document(s) is being deposited with the United States Postal Service as Express Mail No. EL 912884921 US in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231 on 11/9/01

By: Donna Dice
Donna Dice